

Title (en)

Lighting module with separate heat sinks mounted on a common printed circuit board

Title (de)

Beleuchtungsmodul mit verschiedenen Wärmesenken montiert auf einer gemeinsamen Platine

Title (fr)

Module d'éclairage avec des dissipateurs distincts fixés sur la même carte de circuit imprimé

Publication

EP 2730837 B1 20160113 (FR)

Application

EP 13190870 A 20131030

Priority

FR 1260652 A 20121109

Abstract (en)

[origin: EP2730837A1] The module (1) has a light source (2) and a control device (3) that is arranged for controlling the light source, where the light source and the control device are placed on a same printed circuit board (4). A heat sink (8) is arranged for dissipating heat generated by the light source. Another heat sink (9) is intended to dissipate heat generated by the control device. The former heat sink and the latter heat sink are distinct and are connected to the each other by the printed circuit board. The light source includes a LED attached on a portion (6) of the board. The board is of type FR4 type printed circuit board.

IPC 8 full level

F21S 8/10 (2006.01); **F21V 29/00** (2015.01)

CPC (source: EP US)

F21S 41/151 (2017.12 - EP US); **F21S 43/14** (2017.12 - EP); **F21S 45/47** (2017.12 - EP US); **F21S 45/49** (2017.12 - EP); **F21V 29/71** (2015.01 - EP US)

Cited by

EP4397903A1; FR3037127A1; FR3100600A1; US9883612B2; US10342160B2; WO2021044090A1

Designated contracting state (EPC)

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EP 2730837 A1 20140514; **EP 2730837 B1 20160113**; ES 2565429 T3 20160404; FR 2998034 A1 20140516

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